



## Description

### PW N-channel MOSFET

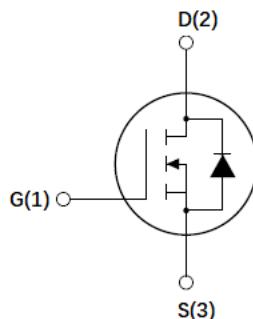
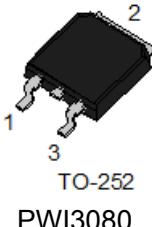
#### Features

- 30V,80A
- $R_{DS(ON)}=4.3m\Omega$  (Typ.) @  $V_{GS}=10V$
- $R_{DS(ON)}=8.8m\Omega$  (Typ.) @  $V_{GS}=4.5V$
- Advanced Trench Technology
- Provide Excellent  $R_{DS(ON)}$  and Low Gate Charge

#### Application

- Load Switch
- PWM Application

#### Package



#### Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise specified)

Symbol	Parameter	Max.		Units
		TO-252		
$V_{DSS}$	Drain-Source Voltage	30		V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$		V
$I_D$	Continuous Drain Current	$T_c = 25^\circ C$	80	A
		$T_c = 100^\circ C$	55	A
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>	350		A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>note2</sup>	265		mJ
$P_D$	Power Dissipation	$T_c = 25^\circ C$	80	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		1.8	$^\circ C/W$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +175	$^\circ C$



## Electrical Characteristics ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	30	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}, V_{GS}=0\text{V}$ ,	-	-	1.0	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0	1.5	2.5	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}, I_D=30\text{A}$	-	4.3	6	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=20\text{A}$	-	8.8	13	
$g_{FS}$	Forward Transconductance	$V_{DS}=5\text{V}, I_D=15\text{A}$	-	25	-	S
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=15\text{V}, V_{GS}=0\text{V}, f=1.0\text{MHz}$	-	2010	-	pF
$C_{oss}$	Output Capacitance		-	327	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	267	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=25\text{V}, I_D=30\text{A}, V_{GS}=10\text{V}$	-	45	-	nC
$Q_{gs}$	Gate-Source Charge		-	3	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	15	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=15\text{V}, I_D=20\text{A}, R_{GEN}=3\Omega, V_{GS}=10\text{V}$	-	21	-	ns
$t_r$	Turn-on Rise Time		-	32	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	59	-	ns
$t_f$	Turn-off Fall Time		-	34	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current	-	-	80	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	350	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}, I_s=20\text{A}$	-	-	1.2	V
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F=20\text{A}, dI/dt=100\text{A}/\mu\text{s}$	-	15	-	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge		-	4	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

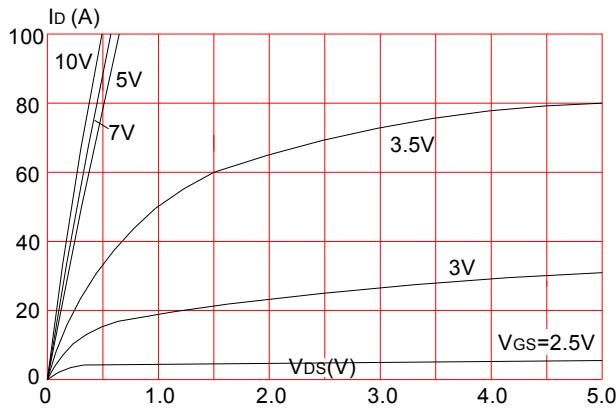
2. EAS condition:  $T_J=25^\circ\text{C}, VDD=30\text{V}, VG=10\text{V}, RG=25\Omega, L=0.5\text{mH}$

3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$

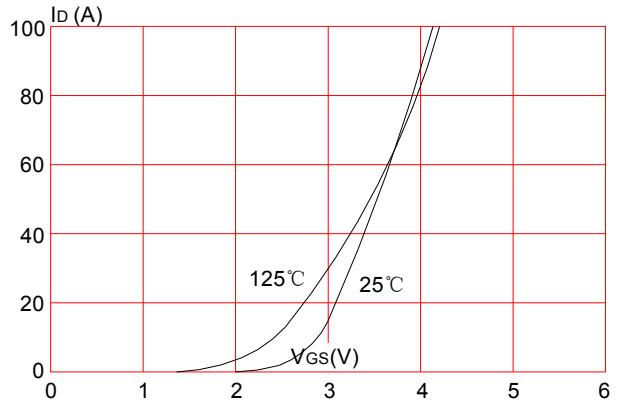


## Typical Performance Characteristics

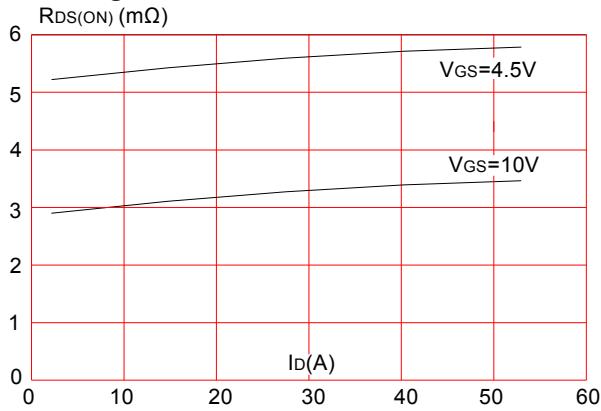
**Figure 1:** Output Characteristics



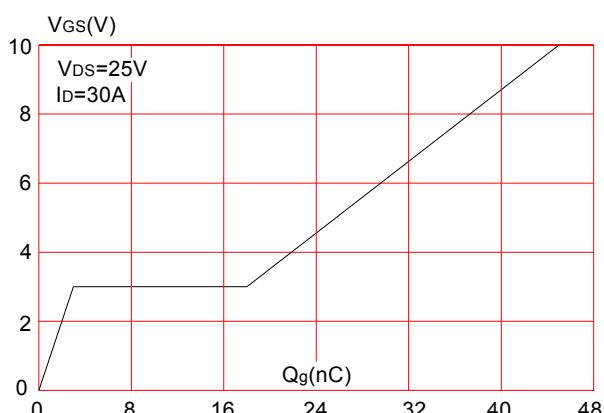
**Figure 2:** Typical Transfer Characteristics



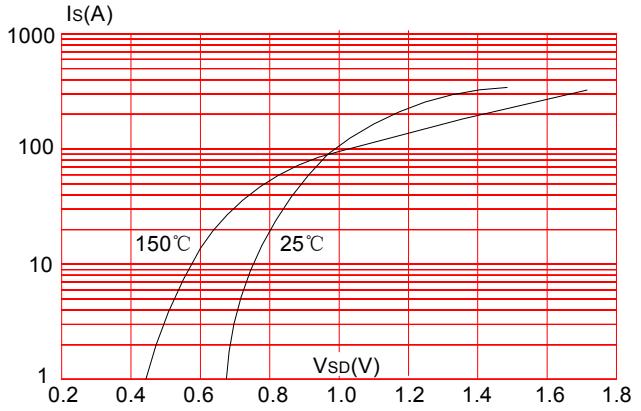
**Figure 3:** On-resistance vs. Drain Current



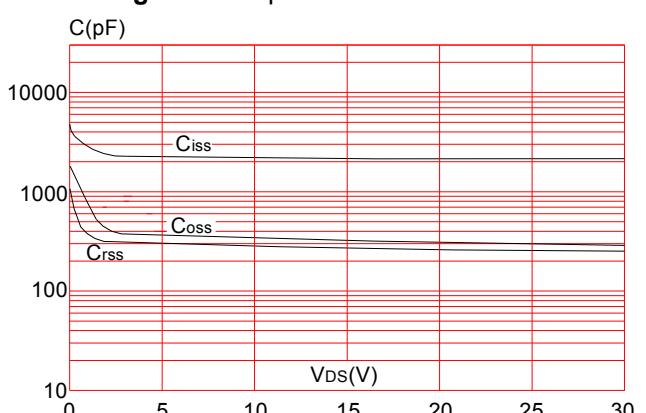
**Figure 5:** Gate Charge Characteristics



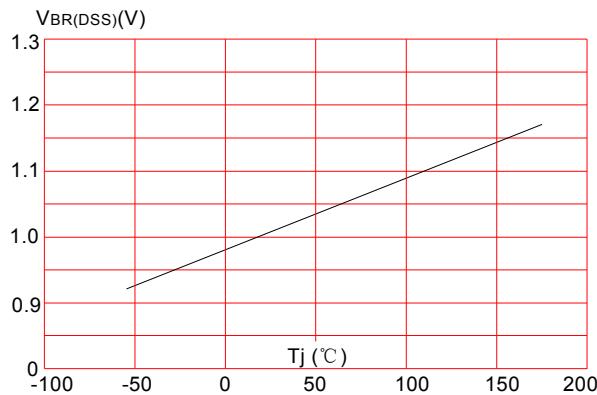
**Figure 4:** Body Diode Characteristics



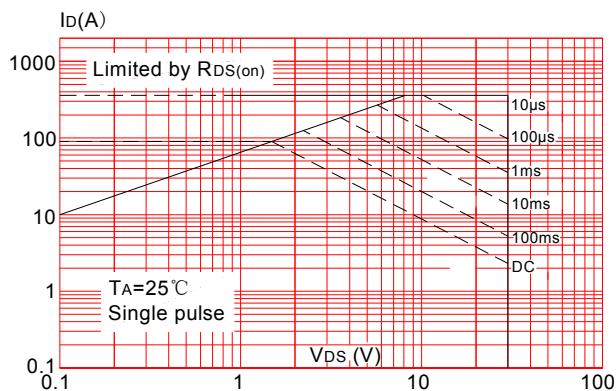
**Figure 6:** Capacitance Characteristics



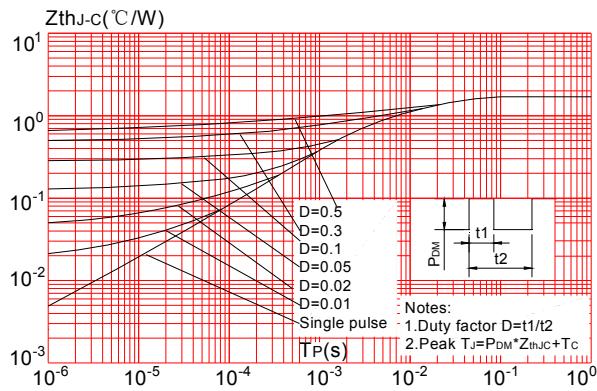
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



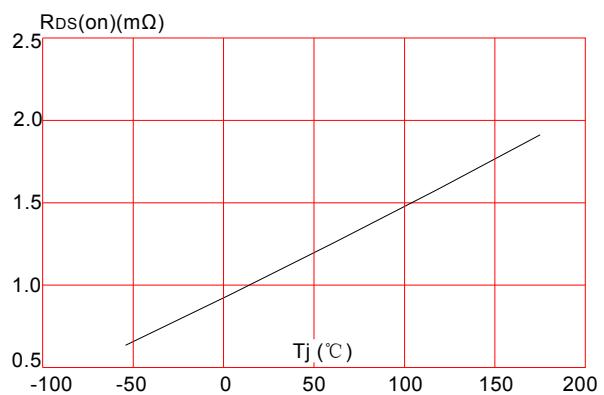
**Figure 9:** Maximum Safe Operating Area



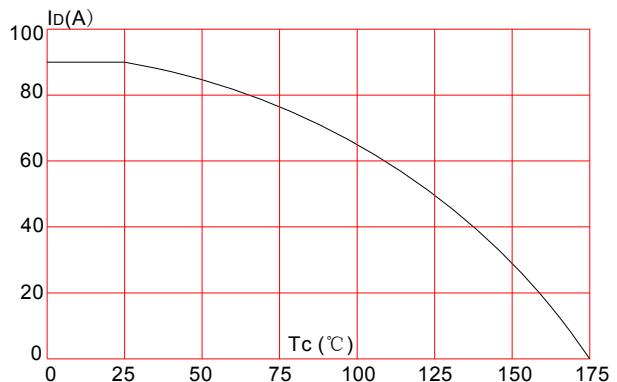
**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case (TO-252)



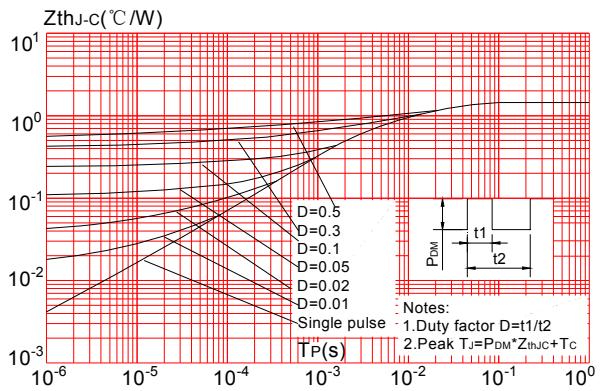
**Figure 8:** Normalized on Resistance vs. Junction Temperature



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case (TO-220C, TO-263)



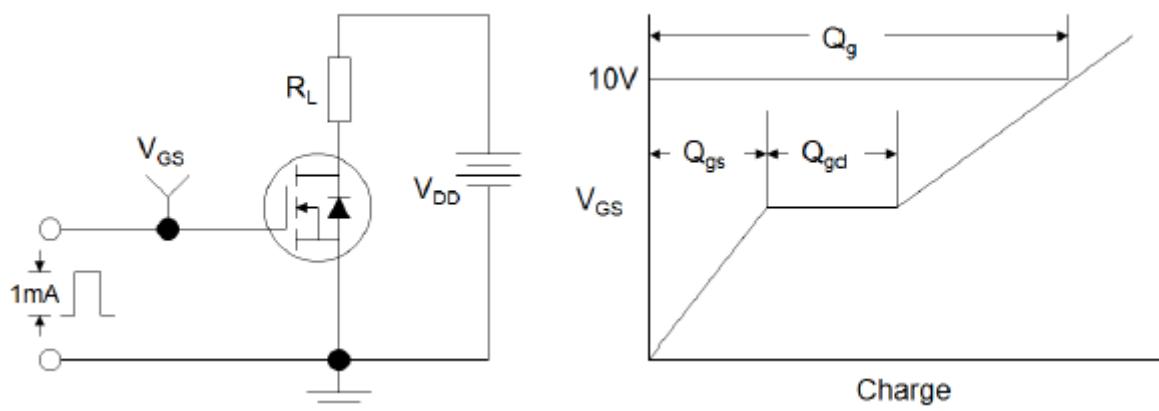


Figure 1: Gate Charge Test Circuit &amp; Waveform

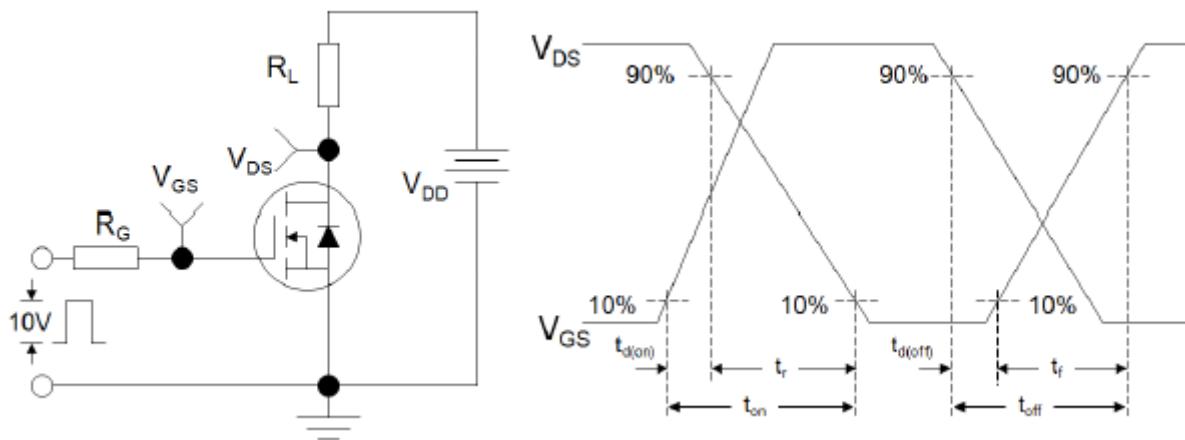


Figure 2: Resistive Switching Test Circuit &amp; Waveforms

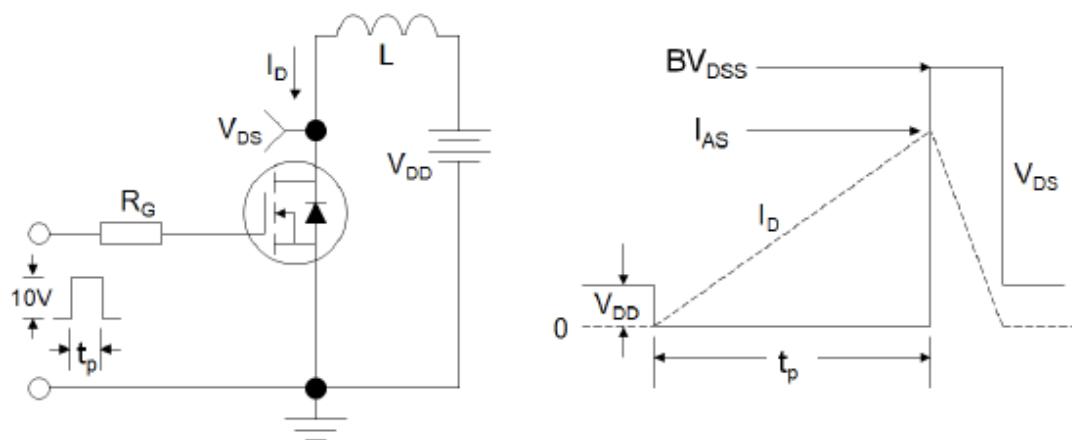
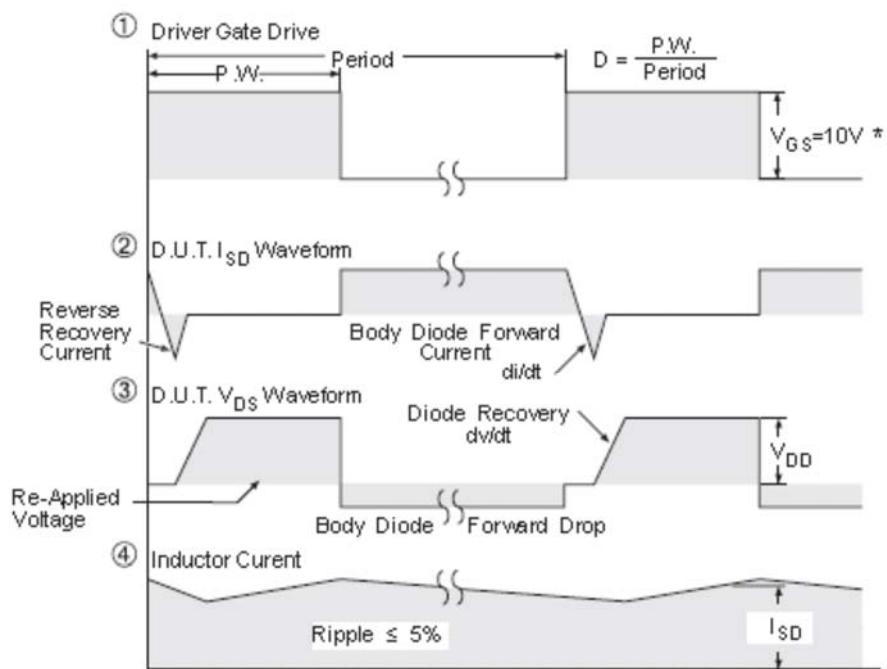
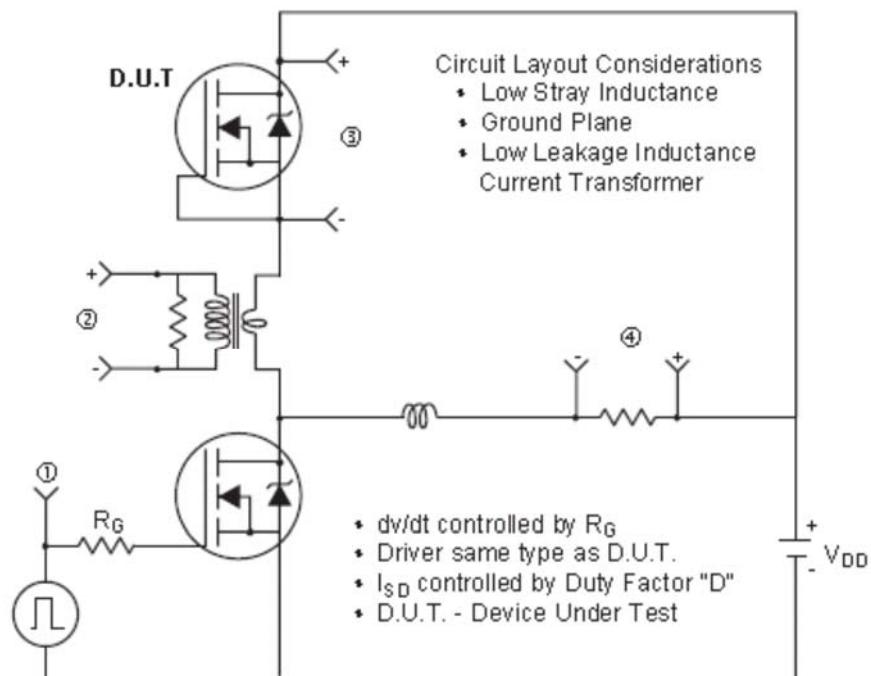


Figure 3: Unclamped Inductive Switching Test Circuit &amp; Waveforms

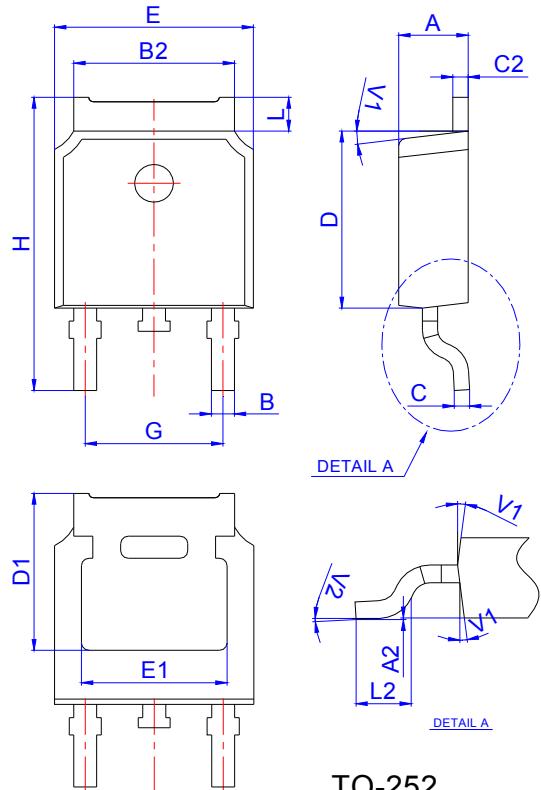


\*  $V_{GS} = 5V$  for Logic Level Devices

Figure 4:Peak Diode Recovery dv/dt Test Circuit & Waveforms (For N-channel)

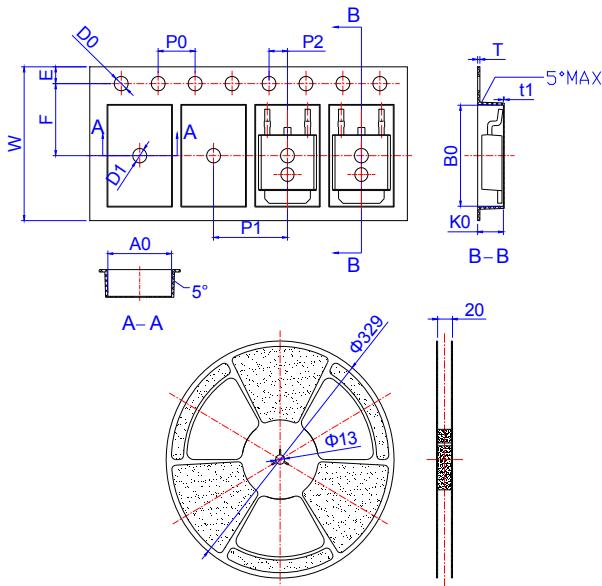


## Package Mechanical Data



TO-252

## Reel Specification-TO-252



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583

OUTLINE	REEL (PCS)	PER CARTON (PCS)	TAPE & REEL
TAPING	2,500	25,000	13inch

Version :C